

**SURFACE MOUNT SCHOTTKY BARRIER DIODE ARRAY**
**Features**

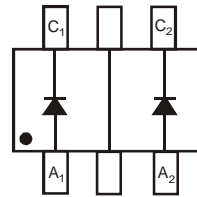
- Low Forward Voltage Drop
- Fast Switching
- Ultra-Small Surface Mount Package
- PN Junction Guard Ring for Transient and ESD Protection
- **Lead Free/RoHS Compliant (Note 3)**
- **"Green" Device (Note 4 and 5)**



Top View

**Mechanical Data**

- Case: SOT-363
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020D
- Terminals: Solderable per MIL-STD-202, Method 208
- Lead Free Plating (Matte Tin Finish annealed over Alloy 42 leadframe).
- Orientation: See Diagram
- Marking Information: See Page 3
- Ordering Information: See Page 3
- Weight: 0.006 grams (approximate)



(Jumper connection between middle pins)

Device Schematic

**Maximum Ratings** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$	30	V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$		
Forward Continuous Current (Note 1)	$I_F$	200	mA
Repetitive Peak Forward Current (Note 1)	$I_{FRM}$	300	mA
Forward Surge Current (Note 1) @ $t < 1.0\text{s}$	$I_{FSM}$	600	mA

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 1)	$P_D$	200	mW
Thermal Resistance, Junction to Ambient Air (Note 1)	$R_{\theta JA}$	625	$^\circ\text{C/W}$
Operating and Storage Temperature Range	$T_J, T_{STG}$	-65 to +125	$^\circ\text{C}$

**Electrical Characteristics** @ $T_A = 25^\circ\text{C}$  unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 2)	$V_{(BR)R}$	30	—	—	V	$I_R = 100\mu\text{A}$
Forward Voltage	$V_F$	—	—	240	mV	$I_F = 0.1\text{mA}$
				320		$I_F = 1\text{mA}$
				400		$I_F = 10\text{mA}$
				500		$I_F = 30\text{mA}$
				1000		$I_F = 100\text{mA}$
Reverse Leakage Current (Note 2)	$I_R$	—	—	2.0	$\mu\text{A}$	$V_R = 25\text{V}$
Total Capacitance	$C_T$	—	—	10	pF	$V_R = 1.0\text{V}, f = 1.0\text{MHz}$
Reverse Recovery Time	$t_{rr}$	—	—	5.0	ns	$I_F = 10\text{mA}$ through $I_R = 10\text{mA}$ to $I_R = 1.0\text{mA}, R_L = 100\Omega$

- Notes:
1. Device mounted on FR-4 PC board with recommended pad layout, which can be found on our website at <http://www.diodes.com/datasheets/ap02001.pdf>.
  2. Short duration pulse test used to minimize self-heating effect.
  3. No purposefully added lead.
  4. Diodes Inc.'s "Green" policy can be found on our website at [http://www.diodes.com/products/lead\\_free/index.php](http://www.diodes.com/products/lead_free/index.php).
  5. Product manufactured with Date Code UO (week 40, 2007) and newer are built with Green Molding Compound. Product manufactured prior to Date Code UO are built with Non-Green Molding Compound and may contain Halogens or Sb2O3 Fire Retardants.

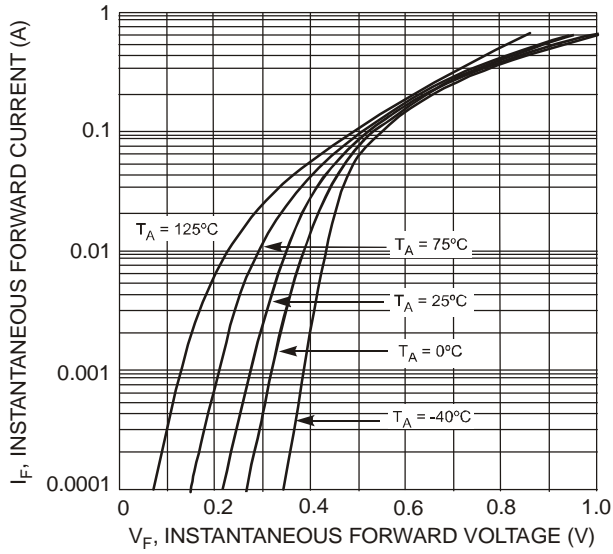


Fig. 1 Typical Forward Characteristics

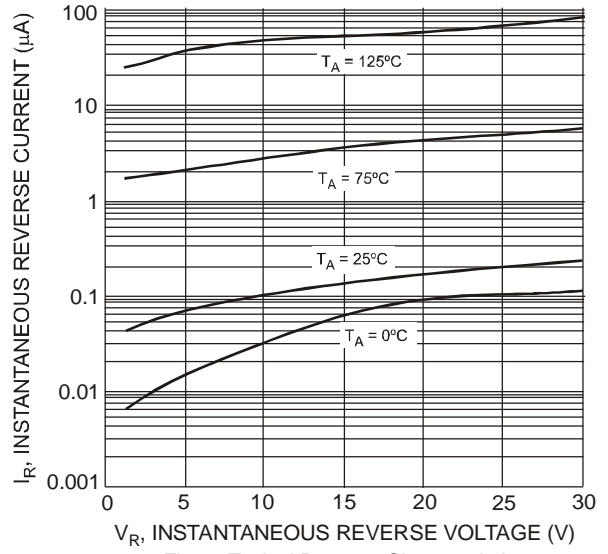


Fig. 2 Typical Reverse Characteristics

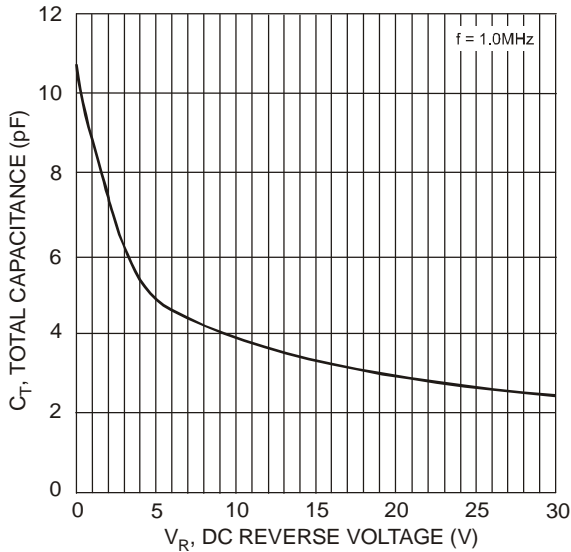


Fig. 3 Total Capacitance vs. Reverse Voltage

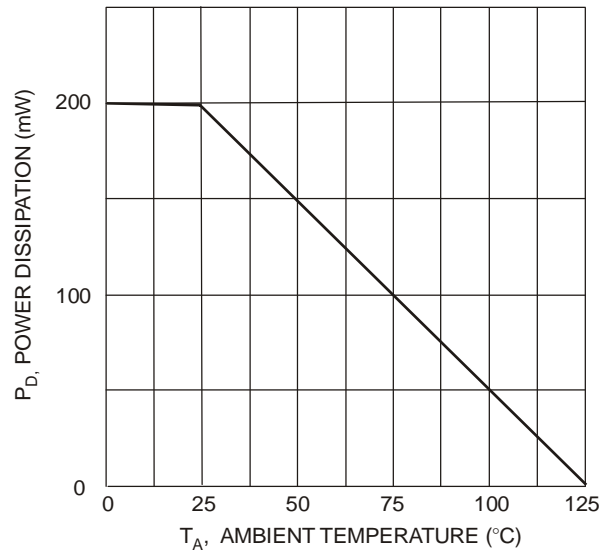


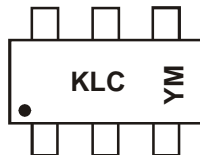
Fig. 4 Power Derating Curve

**Ordering Information** (Note 6)

Part Number	Case	Packaging
BAT54JW-7-F	SOT-363	3000/Tape & Reel

Notes: 6. For packaging details, go to our website at <http://www.diodes.com/datasheets/ap02007.pdf>.

**Marking Information**



KLC = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: N = 2002)  
 M = Month (ex: 9 = September)

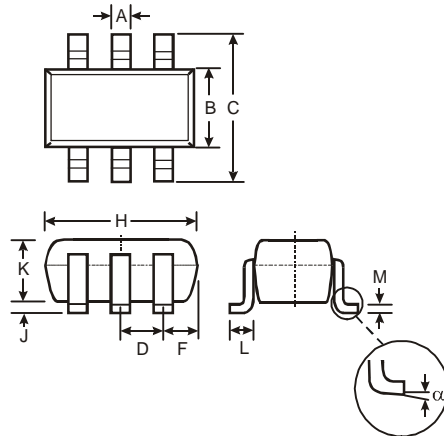
Date Code Key

Year	2001	2002	2003	2004	2005	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015
Code	M	N	P	R	S	T	U	V	W	X	Y	Z	A	B	C

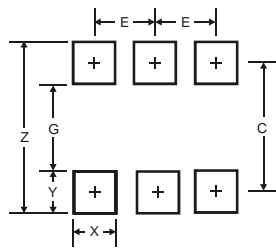
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Package Outline Dimensions**



SOT-363		
Dim	Min	Max
A	0.10	0.30
B	1.15	1.35
C	2.00	2.20
D	0.65 Typ	
F	0.40	0.45
H	1.80	2.20
J	0	0.10
K	0.90	1.00
L	0.25	0.40
M	0.10	0.22
α	0°	8°
All Dimensions in mm		

**Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.5
G	1.3
X	0.42
Y	0.6
C	1.9
E	0.65

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